

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



### Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







# CPI0806KR68R-10

### **UNCONTROLLED DOCUMENT**

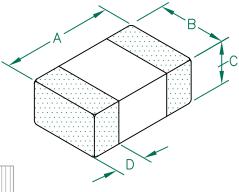
#### PHYSICAL DIMENSIONS:

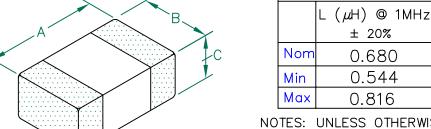
± 0.15[.006] A 2.00 [.079]

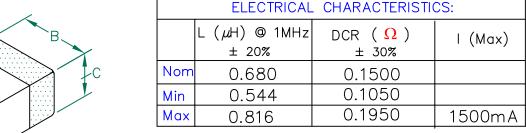
B 1.60 [.063] ± 0.15[.006]

± 0.10[.004] C 0.90 [.035]

D 0.50 [.020] ± 0.20[.008]







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

## 1.5 Inductance(uH) 1.0 0.0

10

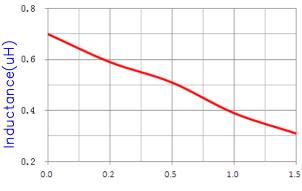
Ls vs Frequency



100

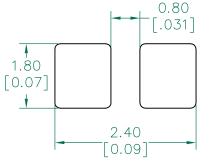
1.000

Ls vs DC BIAS Current



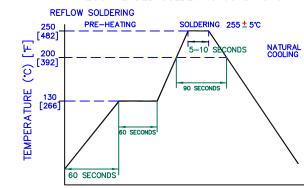
DC BIAS Current (A)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)

#### RECOMMENDED SOLDERING CONDITIONS





	DIMENSIONS ARE IN mm [INCH	This print is the property of Lai	rd							
				Tech, and is loaned in confidence subject to return upon request	and		_ =		T.	
				with the understanding that no			ai	ri	n.	
			copies shall be made without th written consent of Laird Tech. A	e		u I	■ ●			
				rights to design or invention are		_				
				reserved.						
				PROJECT/PART NUMBER:	RE	:v	PART TYPE:	:	DRAWN BY:	
				CPI0806KR68R-10		B CO-FIRI		RE	QU	
В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11	SCALE:	NIT	-c s	HEET:		
B	UPDATE LAIRD LOGO AND NOTES 5 ORIGINAL DRAFT	08/05/13 03/01/11	OΠ	03/01/11	SCALE:	NI	s s		of 2	